

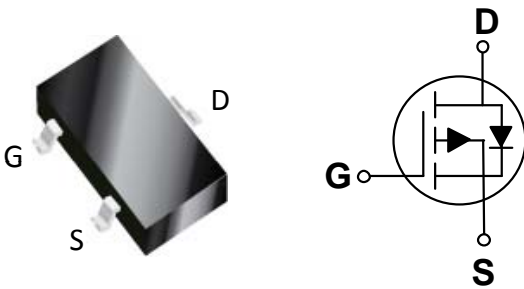


**General Description**

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

<b>BV<sub>DSS</sub></b>	<b>R<sub>DS(ON)</sub></b>	<b>I<sub>D</sub></b>
-30 V	55 mΩ	-4.2 A

SOT-23S Pin Configuration



**Features**

- $R_{DS(ON)} \leq 55m\Omega @ V_{GS} = -10V$
- High power and current handling capability
- Fast switching
- Lead free product is acquired

**Applications**

- PWM applications
- Load Switch
- Power management

**Absolute Maximum Ratings  $T_A=25^\circ C$  unless otherwise noted**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Drain Current - Continuous	-4.2	A
$I_{DM}$	Drain Current - Pulsed (NOTE 1)	-30	A
$P_D$	Power Dissipation	1.2	W
$T_J$	Operating Junction Temperature Range	-50 to 150	$^\circ C$
$T_{STG}$	Storage Temperature Range	-50 to 150	$^\circ C$

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	104	$^\circ C/W$



**Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)**

**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V , I <sub>D</sub> = -250uA	-30	---	---	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> = -24V , V <sub>GS</sub> = 0V	---	---	-1	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> = ±10V , V <sub>DS</sub> = 0V	---	---	±100	nA

**On Characteristics (NOTE 2)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = -10V , I <sub>D</sub> = -4.2A	---	48	55	mΩ
		V <sub>GS</sub> = -4.5V , I <sub>D</sub> = -4A	---	56	75	
		V <sub>GS</sub> = -2.5V , I <sub>D</sub> = -1A	---	72	130	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> = -250uA	-0.7	-1	-1.3	V
gfs	Forward Transconductance	V <sub>DS</sub> = -5V , I <sub>D</sub> = -4.2A	---	10	---	S

**Dynamic and switching Characteristics (NOTE 3)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = -15V , V <sub>GS</sub> = -4.5V , I <sub>D</sub> = -4.2A	---	8.5	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	1.8	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	2.7	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = -15V , V <sub>GS</sub> = -10V , R <sub>GEN</sub> = 6Ω , I <sub>D</sub> = -4.2A	---	7	---	nS
T <sub>r</sub>	Rise Time		---	3	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	30	---	
T <sub>f</sub>	Fall Time		---	12	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -15V , V <sub>GS</sub> = 0V , F= 1MHz	---	880	---	pF
C <sub>oss</sub>	Output Capacitance		---	105	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	65	---	

**Drain-Source Diode Characteristics and Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V <sub>SD</sub>	Diode Forward Voltage (NOTE 2)	V <sub>GS</sub> = 0V , I <sub>S</sub> = -4.2A	---	---	-1.2	V

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Guaranteed by design, not subject to production.



Characteristics Curves

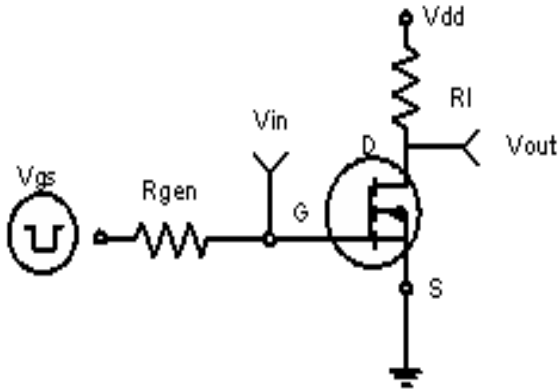


Figure 1 Switching Test Circuit

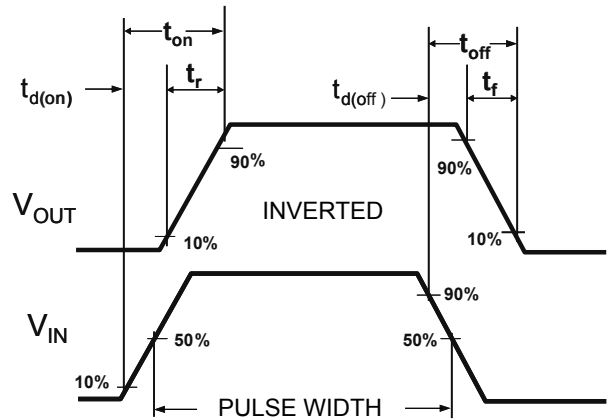


Figure 2 Switching Waveforms

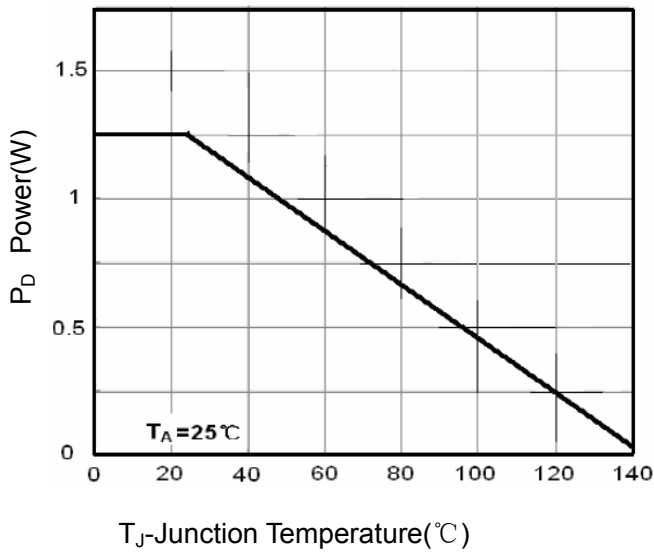


Figure 3 Power Dissipation

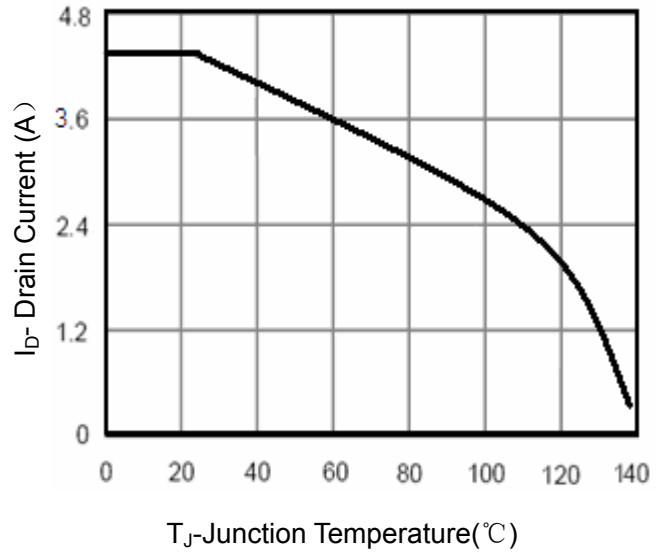


Figure 4 Drain Current

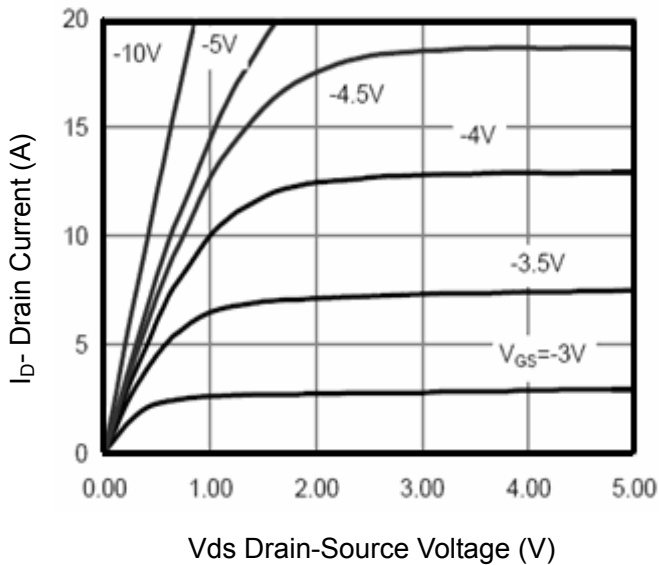


Figure 5 Output Characteristics

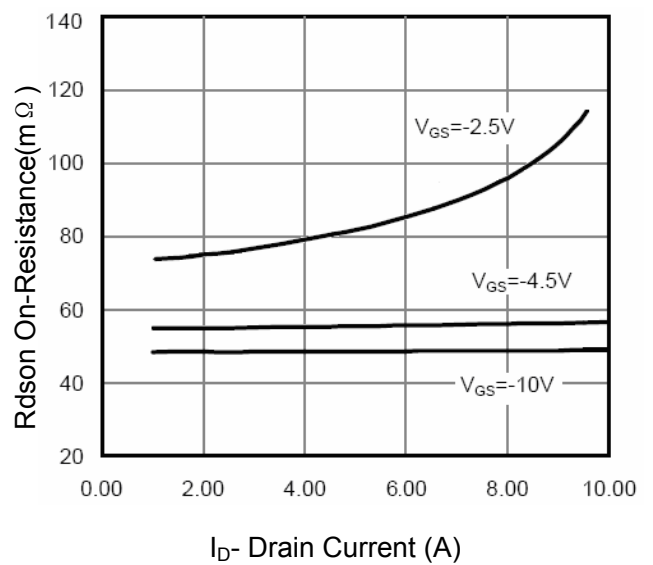


Figure 6 Drain-Source On-Resistance



Characteristics Curves

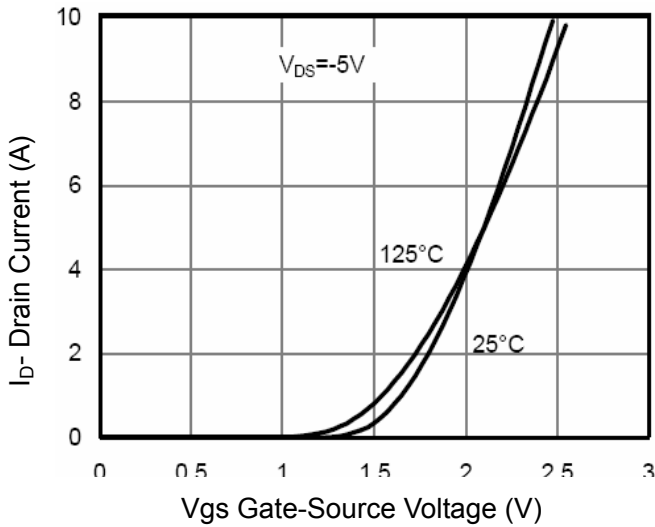


Figure 7 Transfer Characteristics

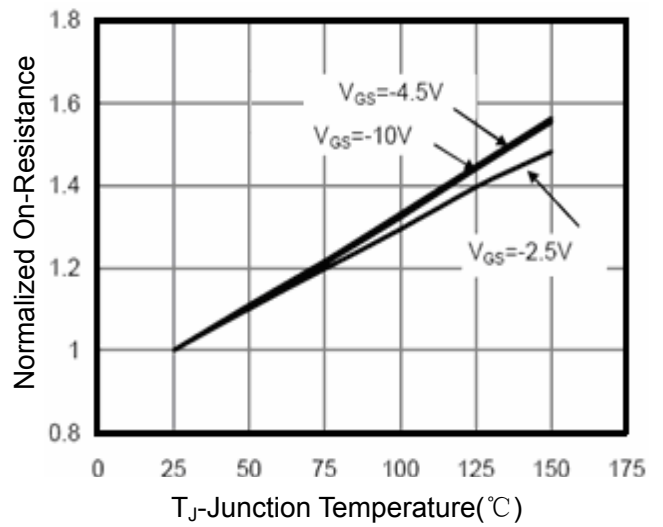


Figure 8 Drain-Source On-Resistance

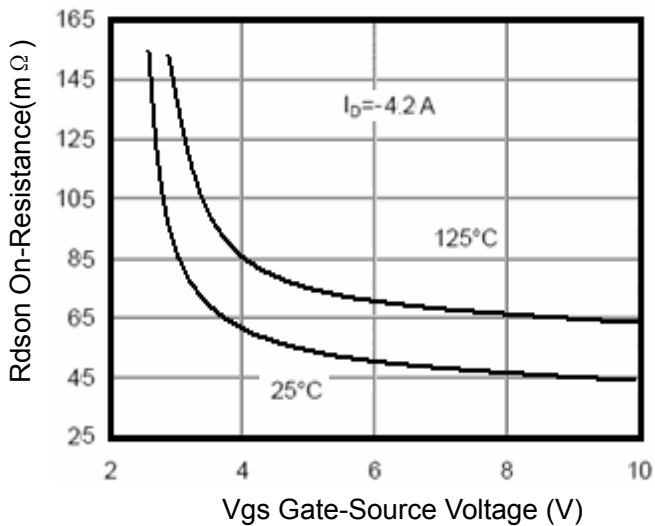


Figure 9 Rdson vs Vgs

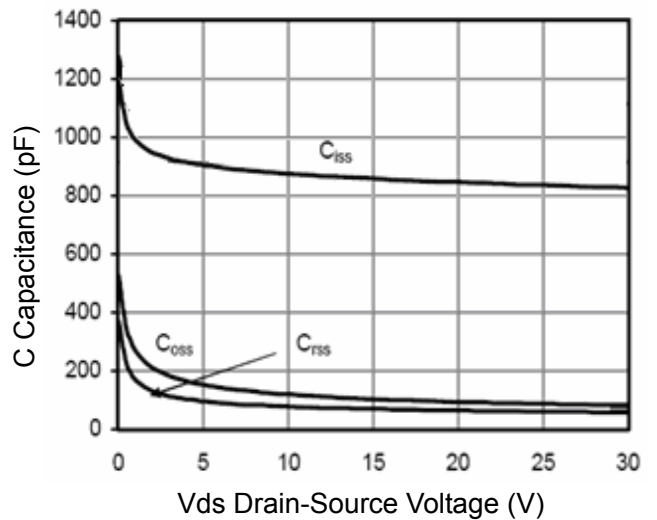


Figure 10 Capacitance vs Vds

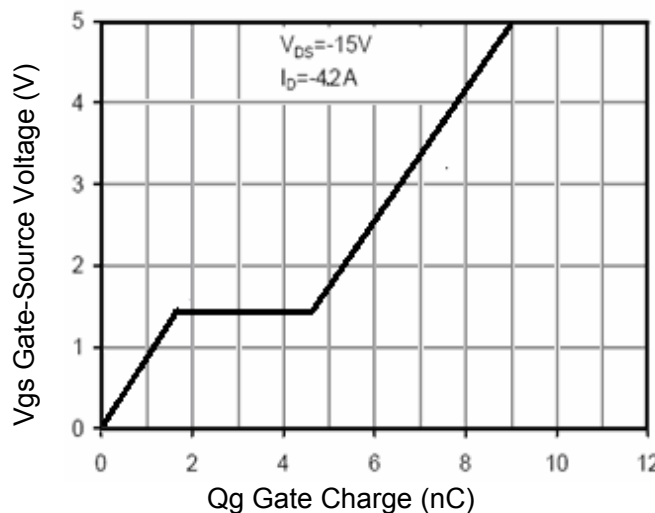


Figure 11 Gate Charge

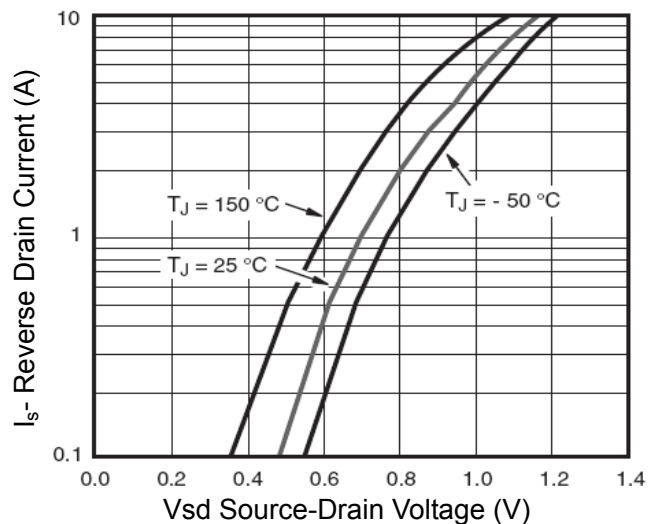


Figure 12 Source- Drain Diode Forward



Characteristics Curves

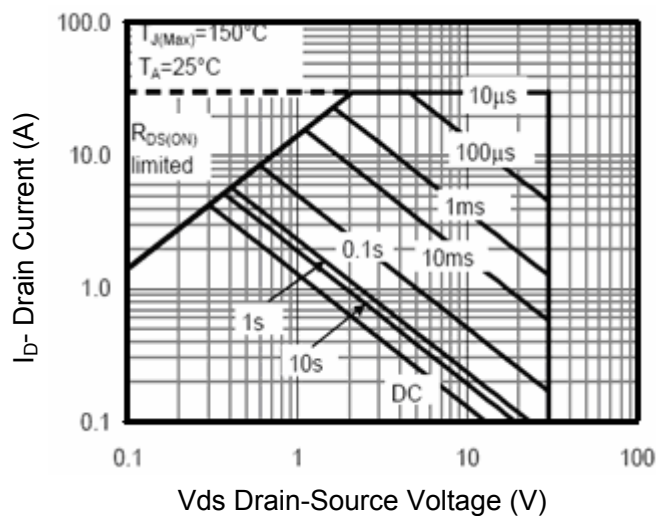


Figure 13 Safe Operation Area

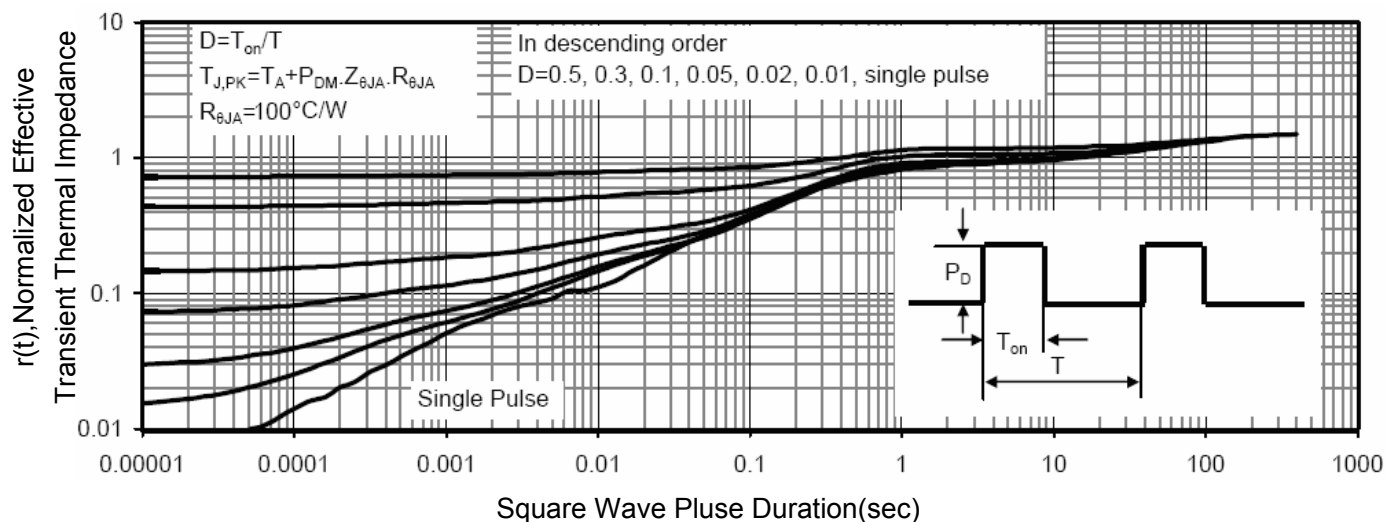
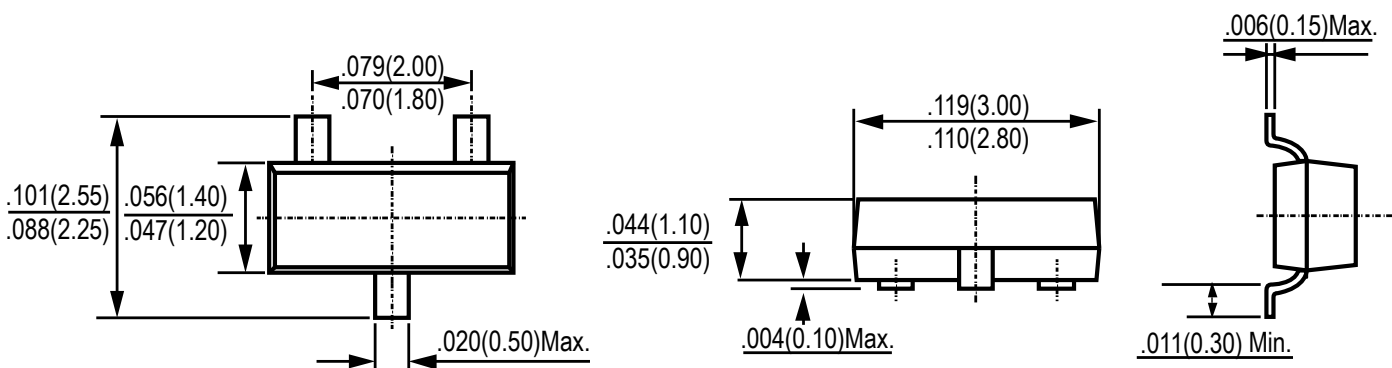


Figure 14 Normalized Maximum Transient Thermal Impedance

Package Outline Dimensions



SOT-23S

Dimensions in inches and (millimeters)



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